

MEG01-004CC

Application no. 09/837,007

November 13, 2006

TO: Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Attn: Art Unit 2891 - Examiner David A Zarneke

FROM: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/837,007
File Date: April 18, 2001
Inventor: M.S. Lin, et al.
Examiner: David A. Zarneke
Art Unit: 2891
Title: A Structure and Manufacturing Method of a Chip Scale Package

RESPONSE TO NON-FINAL OFFICE ACTION

Dear Sir:

The Non-Final Office Action mailed Jul. 12, 2006 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks concerning the above-identified application for patent.

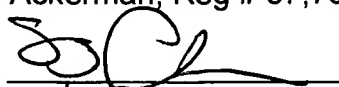
CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on Nov. 13, 2006.

Stephen B. Ackerman, Reg # 37,761

Signature

Date


11/13/06

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Amendments to the Drawings begin on page 7 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 5 of this paper.

An Appendix including replacement drawing figures is attached following page 13 of this paper.